wafer level chip-scale package; 30 bumps; 2.26 x 2.56 x 0.51 mm (backside coating included)

8 February 2016

Package information

1. Package summary

Terminal position code B (bottom)

Package type descriptive code WLCSP

Package type industry code WLCSP30

 Package style descriptive code
 UC (uncased chip)

 Package style suffix code
 NA (not applicable)

Package body material type P (plastic)

Mounting method type S (surface mount)

Issue date 11-6-2015

Table 1. Package summary

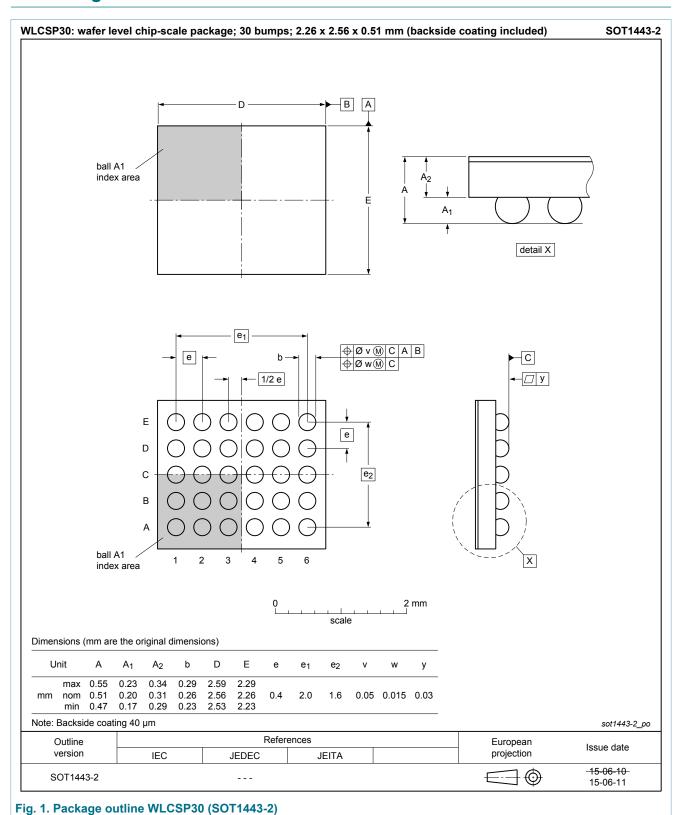
Symbol	Parameter	Min	Тур	Nom	Max	Unit
D	package length	2.53	-	2.56	2.59	mm
E	package width	2.23	-	2.26	2.29	mm
Α	seated height	0.47	-	0.51	0.55	mm
A ₂	package height	0.29	-	0.31	0.34	mm
е	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	30	-	



NXP Semiconductors SOT1443-2

wafer level chip-scale package; 30 bumps; 2.26 x 2.56 x 0.51 mm (backside coating included)

2. Package outline



NXP Semiconductors SOT1443-2

wafer level chip-scale package; 30 bumps; 2.26 x 2.56 x 0.51 mm (backside coating included)

3. Legal information

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